

## Application for Scholarship Bond Deferment or Transfer

**Scholarship** Check ☒ the box (as appropriate)

- ☒ NUS Science & Technology Undergraduate Scholarship
 ☐ Sembcorp Undergraduate Scholarship  
☐ SIA-NOL Undergraduate Scholarship
 ☐ Undergraduate Scholarship for PRC Students

**Bridging Period** Check ☒ the box (as appropriate)

- ☐ NA
 ☐ 20 Months
 ☒ 12 Months
 ☐ 7 Months

Name: Xiang Shang Matric/Student No. A0133890A

Dear scholar,

Upon graduation, you are required to serve your bond in a Singapore entity immediately. To defer your bond for postgraduate studies, overseas work, overseas training or other reasons, or transfer your bond to a Singapore organisation that awarded you a bonded scholarship or training award, you need to fill in this application form **at least 3 months in advance**.

Before you apply, please find out the amount of Banker's Guarantee (BG) required for bond deferment.

Please proceed to apply for **deferment of tuition grant bond** at <https://tgonline.moe.gov.sg> **after** you have obtained approval for the deferment of your scholarship bond.

Please fill in the application form by **typing**, and attach the following supporting documents:

### A. Bond Deferment for Postgraduate Studies

Supporting Documents

Check ☒ the box (as appropriate)

- |  |                                     |
|--|-------------------------------------|
| 1. Colour copy of passport and one of the following: (a) NRIC, (b) Student Pass or (c) Work Pass | <input checked="" type="checkbox"/> |
| 2. Letter of admission for postgraduate course   | <input checked="" type="checkbox"/> |
| 3. Letter of offer of bonded postgraduate scholarship from a Singapore organisation (if any)     | <input type="checkbox"/>            |
| 4. All current and past employment records (if any)  | <input checked="" type="checkbox"/> |

### B. Bond Deferment for Overseas Work or Training

Supporting Documents

Check ☒ the box (as appropriate)

- |   |                          |
|---|--------------------------|
| 1. Colour copy of passport and one of the following: (a) NRIC, (b) Student Pass or (c) Work Pass  | <input type="checkbox"/> |
| 2. Letter of offer of overseas work or training   | <input type="checkbox"/> |
| 3. Letter from HR or company director to show <u>either</u> (if any):<br>(a) Employer is a Singapore-based company* and (1) reasons for posting, (2) start and end date of posting, (3) country posted to, (4) its relationship with the overseas office and (5) percentage of ownership of the overseas office is more than 50%; or<br>(b) HR letter to show that payroll and tax status remains unchanged, i.e. scholar continues to be tax liable in Singapore | <input type="checkbox"/> |
| 4. All current and past employment records (if any)   | <input type="checkbox"/> |

\*with global or regional HQ in Singapore

### C. Bond Transfer

Supporting Documents

Check ☒ the box (as appropriate)

- |  |                          |
|--|--------------------------|
| 1. Colour copy of passport and one of the following: (a) NRIC, (b) Student Pass or (c) Work Pass | <input type="checkbox"/> |
| 2. Letter of offer of bonded scholarship or training award                                       | <input type="checkbox"/> |
| 3. All current and past employment records (if any)  | <input type="checkbox"/> |

LD	IPA	BG/SA/VA (P)	BG/SA/VA (V)	Signed	BG placed

1. Particulars of Applicant			
Name as in NRIC/Passport (include name in <u>Chinese characters</u> , if applicable) Xiang Shang 向尚			
FIN/NRIC S9677458C	Matriculation No. A0133890A	Admission Year 2014	Graduation Year 2018
Name of Course/Title of Degree (if graduated) Bachelor of Science with Honours (Merit) in Applied Mathematics			
Contact Address (Singapore)  461 Clementi Avenue 3 #23-612 Singapore, 120461		Contact Address in Home Country (state in <u>Chinese characters</u> , if applicable)  Wuhan Rongqiao Jinjiang 8-1-4102, China Hubei 430034.  湖北省武汉市桥口区融侨锦江 8-1-4102, 430034	
Contact No. (Singapore) +65 90371449		Contact No. (Home Country) +86 13871238696	
Email Address(es) Xiangshang4@gmail.com			
2. Employment History After Graduation (attach employment records, if any)			
Start Date (Month/Year)	End Date (Month/Year)	Name of Employer	Country of Employment
Jan/2019	July/2021	Mizuho Bank Ltd.	Singapore
3. Previously Approved Bond Deferment (if any)			
First Deferment <input type="checkbox"/> Postgraduate Studies <input type="checkbox"/> Overseas Work or Training <input type="checkbox"/> Others (please specify)		Second Deferment <input type="checkbox"/> Postgraduate Studies <input type="checkbox"/> Overseas Work or Training <input type="checkbox"/> Others (please specify)	
Start Date of 1st deferment	End Date of 1st deferment	Start Date of 2nd deferment	End Date of 2nd deferment
4. Application			
I am applying for <input type="checkbox"/> Bond Deferment for Postgraduate Studies (go to part 4a) <input type="checkbox"/> Bond Deferment for Overseas Work or Training (go to part 4b) <input type="checkbox"/> Bond Deferment for Other Reasons (go to part 4c) <input type="checkbox"/> Bond Transfer (go to part 4d)			
4a. Bond Deferment for Postgraduate Studies			
Name of Institution University of California, Los Angeles	Country of Institution United States	Faculty/School Anderson Management school	Course (indicate if Masters/PhD) Master in Financial Engineering
Start Date Sept 20 2021	End Date Dec 09 2022	Offer of bonded scholarship <input checked="" type="checkbox"/> Nil <input type="checkbox"/> A*STAR <input type="checkbox"/> Others (please specify)	

Date leaving Singapore (applicable if doing postgraduate studies overseas)  
Sept 10<sup>th</sup> 2021

**Plans after completion of postgraduate studies**

After my postgraduate studies, I will:

- ☐ Do postdoctoral work in Singapore to serve my bond  
☒ Do other work in Singapore to serve my bond  
☐ Others (please specify)

**4b. Bond Deferment for Overseas Work or Training**

I am applying for ☐ Overseas Work ☐ Overseas Training

Name of Employer	Country of Work or Training	Address of Work or Training
Start Date	End Date	

Date leaving Singapore

Plans after overseas work or training (please specify)

**4c. Bond Deferment for Other Reasons**

Reason for Deferment (please specify and attach all supporting documents)

Address during Deferment (i.e. where you will be)

Start Date	End Date
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Plans after bond deferment (please specify)

**4d. Bond Transfer**

I am applying to transfer my bond to a Singapore organisation that awarded me a

☐ bonded scholarship ☐ training award

Name of Singapore organisation <input type="checkbox"/> A*STAR <input type="checkbox"/> Others (please specify)	Name of bonded scholarship or training award	
Name of Officer in Charge	Start Date of course	End Date of course
Contact Number of Officer in Charge	Email Address of Officer in Charge	

**5. Updated Particulars of Existing Sureties for Undergraduate Scholarship Agreement**

Name of Surety 1 Qu Zhihua	Name of Surety 2 Xiang Keqin
Surety 1's Home Address (include address in <u>Chinese characters</u> , if applicable) Wuhan Rongqiao Jinjiang 8-1-4102, China Hubei 430034. 湖北省武汉市硚口区融侨锦江 8-1-4102, 430034	Surety 2's Home Address (include address in <u>Chinese characters</u> , if applicable) BLK9-2-301 Wuhan Caidian Qiannianmeili PRC, Hubei 430100 湖北省武汉市蔡甸区千年美丽 9-2-301, 430100
Surety 1's Contact No. +86 13607167372	Surety 2's Contact No. +8613886026386
Surety 1's Email Address	Surety 2's Email Address

1991894558@qq.com	xiangkejian@dpca.com.cn
<b>6. Any Other Information</b>	
Any other relevant information that should be considered by the Sponsor in your application	
<b>7. Declaration and Consent</b>	
<p>a. For applications under part 4a to 4c, should my bond deferment be approved, I agree and undertake to place a Banker's Guarantee <u>in full</u> within 1 month from the approval date of bond deferment and sign a Supplemental Agreement before the start of my bond deferment.</p> <p>b. I declare that I have notified my sureties of this application.</p> <p>c. I declare that all particulars, information and documents given in this application are true and correct to the best of my knowledge and belief, and that I have not wilfully suppressed any material fact. If any of the information given by me in this application is in any way false or incorrect, my application may be rejected, my scholarship may be terminated and I shall be liable to pay liquidated damages.</p> <p>d. I consent to the collection, use and disclosure of this information according to the Personal Data Protection Act.</p>	
Xiang Shang	27/07/2021
Signature of Applicant	Date